

Annex to declaration of accreditation (scope of accreditation)
Normative document: EN ISO/IEC 17025:2005
Registration number: **L 388**

of **MASER Engineering B.V.**
Enschede

This annex is valid from: **14-02-2019** to **30-11-2020**

Replaces annex dated: **28-09-2017**

Location(s) where activities are performed under accreditation

Head Office

Capitool 56
7521 PL
Enschede
The Netherlands

Location	Abbreviation/ location code
Capitool 56 7521 PL Enschede The Netherlands	EN

No.	Material or product	Type of activity¹	Internal reference number	Location
1	Electronic components	Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature, humidity and bias conditions	RF_JESD22-A101 in accordance with JESD22-A101 RF_JESD22-A110 in accordance with JESD22-A110	EN
2		Exposure of electronic components to calibrated and controlled temperature and humidity conditions	RF_JESD22-A102 in accordance with JESD22-A102 RF_JESD22-A118 in accordance with JESD22-A118 RF_IEC 60068-2-78 in accordance with IEC 60068-2-78	EN

This annex has been approved by the Board of the
Dutch Accreditation Council, on its behalf,

J.A.W.M. de Haas
Director of Operations

¹ If there is a referral to a code starting with NAW, NAP, EA or IAF, this concerns a scheme mentioned on the [RvA-BR010-lijst](#).
If no date or version number is mentioned for a normative document, the accreditation concerns the most current version of the document or scheme.

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No.	Material or product	Type of activity ¹	Internal reference number	Location
3	Electronic components	Exposure of electronic components to calibrated and controlled high temperature conditions	RF_JESD22-A103 in accordance with JESD22-A103 RF_IEC 60068-2-2 in accordance with IEC 60068-2-2 RF_MIL-STD-883 m1008 in accordance with MIL-STD-883, method 1008	EN
4		Exposure of electronic components to calibrated and controlled alternating temperature conditions	RF_JESD22-A104 in accordance with JESD22-A104 RF_IEC 60068-2-14 in accordance with IEC 60068-2-14 RF_MIL-STD-883 m1010 in accordance with MIL-STD-883, method 1010	EN
5		Exposure of heat-dissipating electronic components to calibrated and controlled alternating bias and alternating temperature conditions	RF_JESD22-A105 in accordance with JESD22-A105	EN
6		Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature and bias conditions	RF_JESD22-A108 in accordance with JESD22-A108 RF_AEC Q100-008 in accordance with AEC Q100-008	EN
7		Exposure of electronic components to calibrated and controlled low temperature conditions	RF_JESD22-A119 in accordance with JESD22-A119 RF_IEC 60068-2-1 in accordance with IEC 60068-2-1	EN
8		Exposure of electronic components to calibrated and controlled alternating temperature and alternating humidity conditions	RF_IEC 60068-2-30 in accordance with IEC 60068-2-30	EN
9		Exposure of electronic components to calibrated and controlled alternating humidity, alternating temperature and bias conditions	RF_JESD22-A100 in accordance with JESD22-A100 RF_IEC 60068-2-38 in accordance with IEC 60068-2-38 RF_MIL-STD-883 m1004 in accordance with MIL-STD-883, method 1004	EN

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No.	Material or product	Type of activity ¹	Internal reference number	Location
10	Electronic components	Exposure of bond wires of electronic components to calibrated and controlled pull forces	RF_MIL-STD-883 m2011 in accordance with MIL-STD-883, method 2011	EN
11		Exposure of bond wires, dies or solderballs of electronic components to calibrated and controlled shear forces	RF_MIL-STD-883 m2019 in accordance with MIL-STD-883, method 2019 RF_AEC Q100-001 in accordance with AEC Q100-001 RF_AEC Q100-010 in accordance with AEC Q100-010 RF_JESD22-B116 in accordance with JESD22-B116 RF_JESD22-B117 in accordance with JESD22-B117	EN